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**Speech subject:** AI Assisted Electronic Packaging Technology and Reliability Evaluation

**Speech leader:** Yanwei DAI—Associate Professor, Beijing University of Technology

**Speech Description/Objective:**

Artificial intelligence science is widely considered as the fourth paradigm of the scientific discovery. Artificial intelligence based theories and methods have achieved some more recent progresses in scientific research and engineering applications in different disciplines. The research progress of artificial intelligence methods has also brought new development opportunities to the electronic packaging industry. In view of the current difficulties in the evaluation of integrated circuit packaging technology and reliability, this report will focus on the latest research progress of our group in the field of data-driven methods in electronic packaging. This report will also present some typical existing data-driven methods in electronic packaging in detail. Summary and comments on those methods will be also made accordingly. The possible development direction, frontier, and challenges of data-driven methods in the field of electronic packaging in the future will be finally discussed and outlooked.

**Speech Outline:**

Firstly, the background of the related studies will be given. Then, the more recent progress of some data-driven methods will be reported. Last but not least, the future trends and prospects in this field will be discussed.

**Who Should Attend:**

Scientific researchers, technique staff, and students in the field of integrated circuit packaging.

**Introduction of Speaker:**

Dr. Yanwei DAI is an associate professor at Beijing University of Technology. He was selected as a Young Talent Lifting Project of Beijing Association for Science and Technology and a Young Outstanding Talent of Beijing University of Technology's high-level talent plan. His main research interests are integrated circuit packaging technology and reliability. Dr. Dai has presided some projects of the National Natural Science Foundation of China, the Beijing Natural Science Foundation, the Aeronautical Science Foundation, etc., and some projects granted by several leading enterprises in the field of integrated circuits. He has published more than 70 SCI-indexed journal papers in authoritative journals in the field of solids mechanics and integrated circuit packaging, including 46 SCI journal papers as the first/corresponding author. He has served as a young editorial board, editorial board member or guest editor of two Chinese scientific journals and two international academic journals.